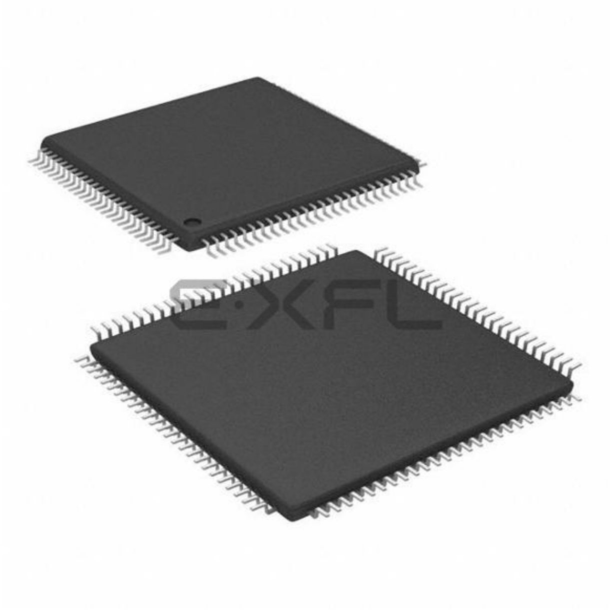
Microchip Technology - DSPIC33FJ64GP310AT-I/PF Datasheet



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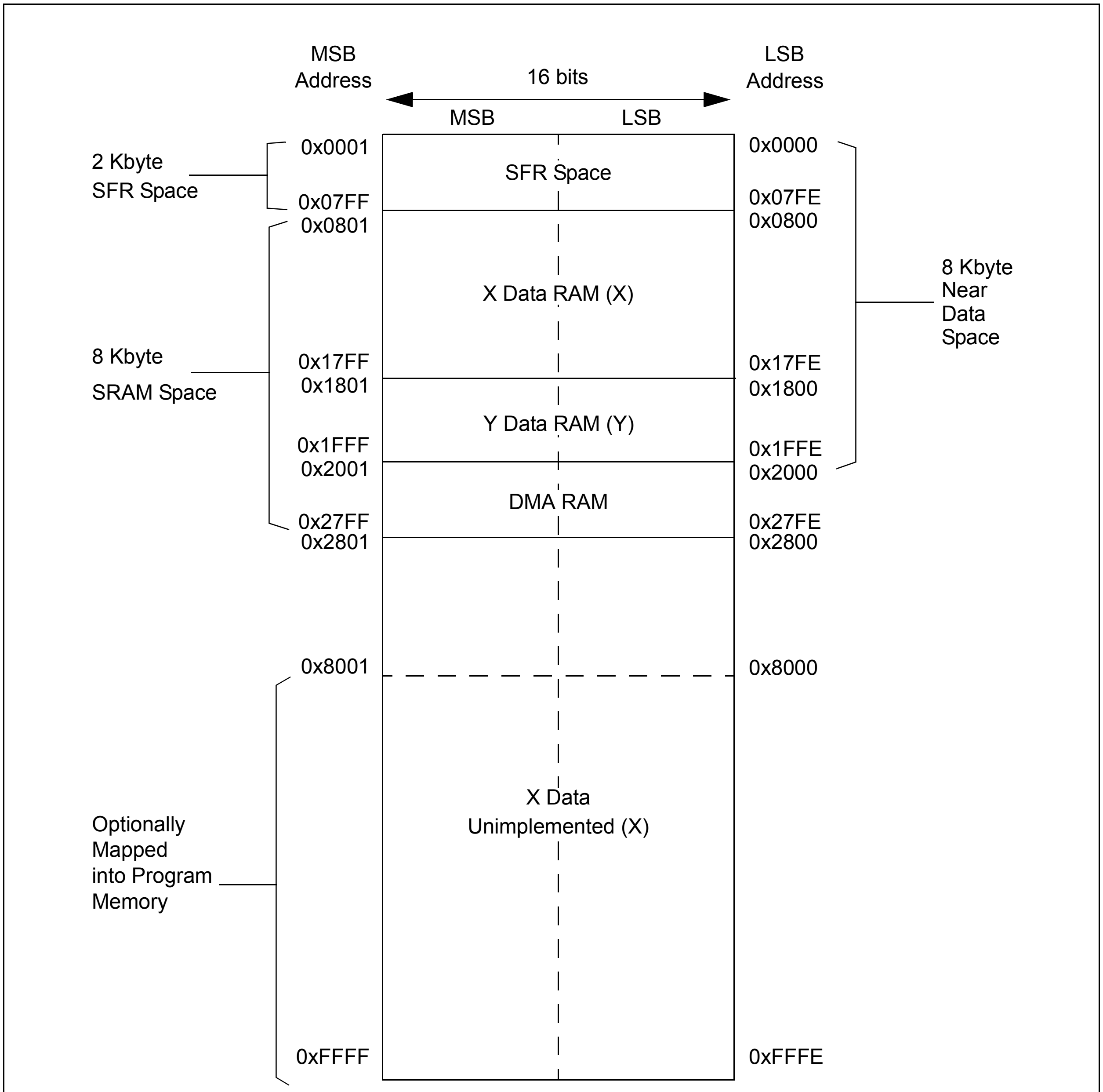
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	85
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp310at-i-pf

FIGURE 4-3: DATA MEMORY MAP FOR dsPIC33FJXXXGPX06A/X08A/X10A DEVICES WITH 8 KBS RAM



after modification) must, therefore, be valid addresses within X data space for W8 and W9 and Y data space for W10 and W11.

Note:	Register Indirect with Register Offset Addressing mode is only available for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the `MAC` class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.3.5 OTHER INSTRUCTIONS

Besides the various addressing modes outlined above, some instructions use literal constants of various sizes. For example, `BRA` (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the `DISI` instruction uses a 14-bit unsigned literal field. In some instructions, such as `ADD Acc`, the source of an operand or result is implied by the opcode itself. Certain operations, such as `NOP`, do not have any operands.

4.4 Modulo Addressing

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either data or program space (since the data pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into program space) and Y data spaces. Modulo Addressing can operate on any W register pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can only be configured to operate in one direction as there are certain restrictions on the buffer start address (for incrementing buffers), or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers which have a power-of-2 length. As these buffers satisfy the start and end address criteria, they may operate in a bidirectional mode (i.e., address boundary checks will be performed on both the lower and upper address boundaries).

4.4.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y space Modulo Addressing EA calculations assume word sized data (LSb of every EA is always clear).

9.2 Clock Switching Operation

Applications are free to switch between any of the four clock sources (Primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects that could result from this flexibility, dsPIC33FJXXXGPX06A/X08A/X10A devices have a safeguard lock built into the switch process.

Note:	Primary Oscillator mode has three different submodes (XT, HS and EC) which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch between the different primary submodes without reprogramming the device.

9.2.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the Configuration register must be programmed to '`0`'. (Refer to **Section 22.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('`1`'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSC control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSC bits (OSCCON<14:12>) reflect the clock source selected by the FNOSC Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled. It is held at '`0`' at all times.

9.2.2 OSCILLATOR SWITCHING SEQUENCE

At a minimum, performing a clock switch requires this basic sequence:

1. If desired, read the COSC bits (OSCCON<14:12>) to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSC control bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSC status bits with the new value of the NOSC control bits. If they are the same, then the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the status bits, LOCK (OSCCON<5>) and CF (OSCCON<3>) are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = `1`).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSC bit values are transferred to the COSC status bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM are enabled) or LP (if LPOSCEN remains set).

Note 1:	The processor continues to execute code throughout the clock switching sequence. Timing sensitive code should not be executed during this time.
2:	Direct clock switches between any primary oscillator mode with PLL and FRC-PLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.
3:	Refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

9.3 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by programming. If the FSCM function is enabled, the LPRC internal oscillator runs at all times (except during Sleep mode) and is not subject to control by the Watchdog Timer.

In the event of an oscillator failure, the FSCM generates a clock failure trap event and switches the system clock over to the FRC oscillator. Then the application program can either attempt to restart the oscillator or execute a controlled shutdown. The trap can be treated as a warm Reset by simply loading the Reset address into the oscillator fail trap vector.

If the PLL multiplier is used to scale the system clock, the internal FRC is also multiplied by the same factor on clock failure. Essentially, the device switches to FRC with PLL on a clock failure.

17.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXGPX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. “Inter-Integrated Circuit™ (I^2C™)”** (DS70195) in the *“dsPIC33F/PIC24H Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Inter-Integrated Circuit (I^2C) module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The dsPIC33FJXXXGPX06A/X08A/X10A devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module ‘x’ (x = 1 or 2) offers the following key features:

- I^2C interface supporting both master and slave operation
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7-bit and 10-bit addressing
- I^2C Port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation; detects bus collision and will arbitrate accordingly

17.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I^2C module can operate either as a slave or a master on an I^2C bus.

The following types of I^2C operation are supported:

- I^2C slave operation with 7-bit addressing
- I^2C slave operation with 10-bit addressing
- I^2C master operation with 7-bit or 10-bit addressing

For details about the communication sequence in each of these modes, please refer to the “*dsPIC33F/PIC24H Family Reference Manual”*.

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1 HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0 HC	R/W-0 HC	R/W-0 HC	R/W-0 HC	R/W-0 HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	U = Unimplemented bit, read as ‘0’		
R = Readable bit	W = Writable bit	HS = Set in hardware	HC = Cleared in hardware
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit

1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module. All I^{2}C pins are controlled by port functions

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **I2CSIDL:** Stop in Idle Mode bit

1 = Discontinue module operation when device enters an Idle mode
0 = Continue module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^{2}C slave)

1 = Release SCLx clock
0 = Hold SCLx clock low (clock stretch)

If STREN = 1:
Bit is R/W (i.e., software may write ‘0’ to initiate stretch and write ‘1’ to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.

If STREN = 0:
Bit is R/S (i.e., software may only write ‘1’ to release clock). Hardware clear at beginning of slave transmission.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit

1 = IPMI mode is enabled; all addresses Acknowledged
0 = IPMI mode disabled

bit 10 **A10M:** 10-bit Slave Address bit

1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit

1 = Slew rate control disabled
0 = Slew rate control enabled

bit 8 **SMEN:** SMBus Input Levels bit

1 = Enable I/O pin thresholds compliant with SMBus specification
0 = Disable SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I^{2}C slave)

1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^{2}C slave)

Used in conjunction with SCLREL bit.
1 = Enable software or receive clock stretching
0 = Disable software or receive clock stretching

18.1 UART Helpful Tips

1. In multi-node direct-connect UART networks, UART receive inputs react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the idle state, the default of which is logic high, (i.e., URXINV = `0`). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a start bit detection and will cause the first byte received after the device has been initialized to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin depending on the value of the URXINV bit.
    a) If URXINV = `0`, use a pull-up resistor on the RX pin.
    b) If URXINV = `1`, use a pull-down resistor on the RX pin.
2. The first character received on a wake-up from Sleep mode caused by activity on the UxRX pin of the UART module will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock relative to the incoming UxRX bit timing is no longer synchronized, resulting in the first character being invalid. This is to be expected.

18.2 UART Resources

Many useful resources related to UART are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en546064

18.2.1 KEY RESOURCES

- **Section 17. “UART”** (DS70188)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 20-2: DCICON2: DCI CONTROL REGISTER 2

U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-0
—	—	—	—	BLEN<1:0>		—	COFSG3
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
COFSG<2:0>			—	WS<3:0>			
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12	**Unimplemented:** Read as ‘`0`’
bit 11-10	**BLEN<1:0>:** Buffer Length Control bits `11` = Four data words will be buffered between interrupts `10` = Three data words will be buffered between interrupts `01` = Two data words will be buffered between interrupts `00` = One data word will be buffered between interrupts
bit 9	**Unimplemented:** Read as ‘`0`’
bit 8-5	**COFSG<3:0>:** Frame Sync Generator Control bits `1111` = Data frame has 16 words • • • `0010` = Data frame has 3 words `0001` = Data frame has 2 words `0000` = Data frame has 1 word
bit 4	**Unimplemented:** Read as ‘`0`’
bit 3-0	**WS<3:0>:** DCI Data Word Size bits `1111` = Data word size is 16 bits • • • `0100` = Data word size is 5 bits `0011` = Data word size is 4 bits `0010` = **Invalid Selection**. Do not use. Unexpected results may occur `0001` = **Invalid Selection**. Do not use. Unexpected results may occur `0000` = **Invalid Selection**. Do not use. Unexpected results may occur

NOTES:

22.0 SPECIAL FEATURES

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJXXXGPX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. “CodeGuard™ Security”** (DS70199), **Section 24. “Programming and Diagnostics”** (DS70207), and **Section 25. “Device Configuration”** (DS70194) in the *“dsPIC33F/PIC24H Family Reference Manual”*, which are available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

dsPIC33FJXXXGPX06A/X08A/X10A devices include the following features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

22.1 Configuration Bits

dsPIC33FJXXXGPX06A/X08A/X10A devices provide nonvolatile memory implementation for device configuration bits. Refer to **Section 25. “Device Configuration”** (DS70194) of the *“dsPIC33F/PIC24H Family Reference Manual”*, for more information on this implementation.

The Configuration bits can be programmed (read as ‘0’), or left unprogrammed (read as ‘1’), to select various device configurations. These bits are mapped starting at program memory location 0xF80000.

The device Configuration register map is shown in Table 22-1.

The individual Configuration bit descriptions for the Configuration registers are shown in Table 22-2.

Note that address 0xF80000 is beyond the user program memory space. In fact, it belongs to the configuration memory space (0x800000-0xFFFFFF) which can only be accessed using table reads and table writes.

TABLE 22-1: DEVICE CONFIGURATION REGISTER MAP

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FBS	RBS<1:0>		—	—	BSS<2:0>			BWRP
0xF80002	FSS	RSS<1:0>		—	—	SSS<2:0>			SWRP
0xF80004	FGS	—	—	—	—	—	GSS1	GSS0	GWRP
0xF80006	FOSCSEL	IESO	Reserved(2)	—	—	—	FNOSC<2:0>		
0xF80008	FOSC	FCKSM<1:0>		—	—	—	OSCIOFNC	POSCMD<1:0>	
0xF8000A	FWDT	FWDTEN	WINDIS	PLLKEN(3)	WDTPRE	WDTPOST<3:0>			
0xF8000C	FPOR	Reserved(4)			—	—	FPWRT<2:0>		
0xF8000E	FICD	Reserved(1)		JTAGEN	—	—	—	ICS<1:0>	
0xF80010	FUID0	User Unit ID Byte 0							
0xF80012	FUID1	User Unit ID Byte 1							
0xF80014	FUID2	User Unit ID Byte 2							
0xF80016	FUID3	User Unit ID Byte 3							

Legend: — = unimplemented bit, read as ‘0’.

Note 1: These bits are reserved for use by development tools and must be programmed as ‘1’.

2: When read, this bit returns the current programmed value.

3: This bit is unimplemented on dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A devices and reads as ‘0’.

4: These bits are reserved and always read as ‘1’.

TABLE 25-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**[1]	**Min**[1]	**Typ**	**Max**[1]	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.40	—	2.55	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 25-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**[3]	**Min**	**Typ**[1]	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132b	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	
D136a	TRW	Row Write Time	1.32	—	1.74	ms	TRW = 11064 FRC cycles, TA = +85°C, See **Note 2**
D136b	TRW	Row Write Time	1.28	—	1.79	ms	TRW = 11064 FRC cycles, TA = +150°C, See **Note 2**
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, See **Note 2**
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +150°C, See **Note 2**
D138a	TWW	Word Write Cycle Time	42.3	—	55.9	µs	TWW = 355 FRC cycles, TA = +85°C, See **Note 2**
D138b	TWW	Word Write Cycle Time	41.1	—	57.6	µs	TWW = 355 FRC cycles, TA = +150°C, See **Note 2**

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `b'011111` (for Min), TUN<5:0> = `b'100000` (for Max). This parameter depends on the FRC accuracy (see Table 25-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time see **Section 5.3 “Programming Operations”**.

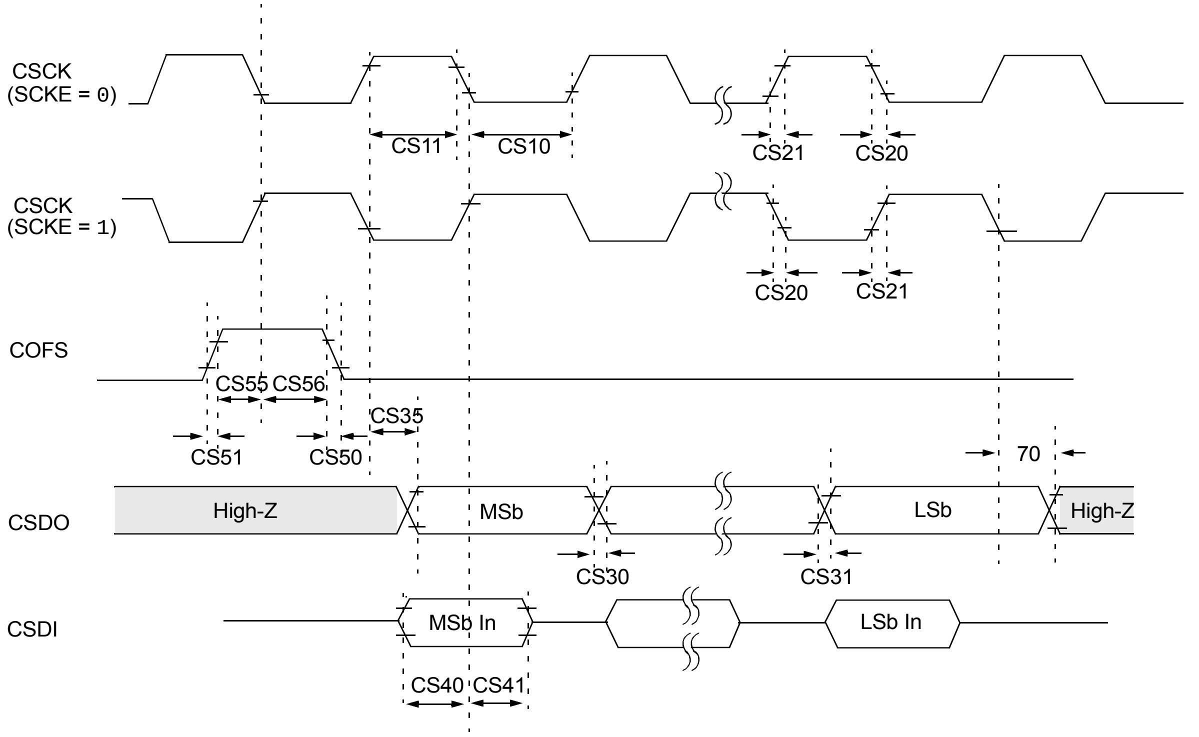
3: These parameters are assured by design, but are not characterized or tested in manufacturing.

TABLE 25-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
—	CEFC	External Filter Capacitor Value[1]	4.7	10	—	µF	Capacitor must be low series resistance (< 5 ohms)

Note 1: Typical VCORE voltage = 2.5V when VDD ≥ VDDMIN.

FIGURE 25-21: DCI MODULE (MULTI-CHANNEL, I^{2}S MODES) TIMING CHARACTERISTICS



Note: Refer to Figure 25-1 for load conditions.

26.1 High Temperature DC Characteristics

TABLE 26-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33FJXXXGPX06A/X08A/X10A
HDC5	VBOR to 3.6V[1]	-40°C to +150°C	20

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 25-11 for the minimum and maximum BOR values.

TABLE 26-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: PINT = VDD x (IDD - Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD - VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ - TA)/θJA			W

TABLE 26-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Operating Voltage							
HDC10	**Supply Voltage**						
	VDD	—	3.0	3.3	3.6	V	-40°C to +150°C

TABLE 26-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current[1,3]

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

26.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJXXXGPX06A/X08A/X10A AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 25.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 25.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 26-7: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature Operating voltage V_{DD} range as described in Table 26-1.

FIGURE 26-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

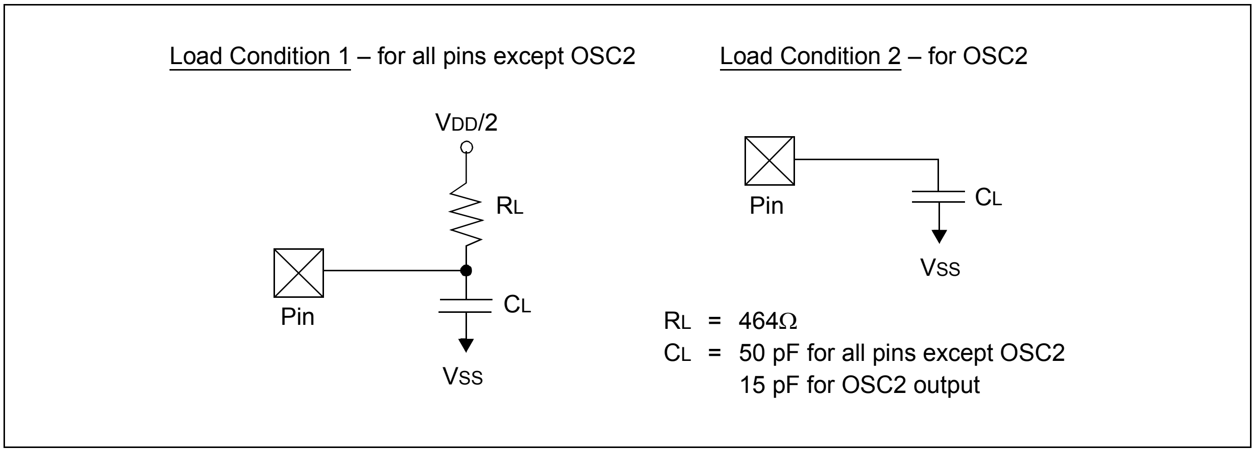


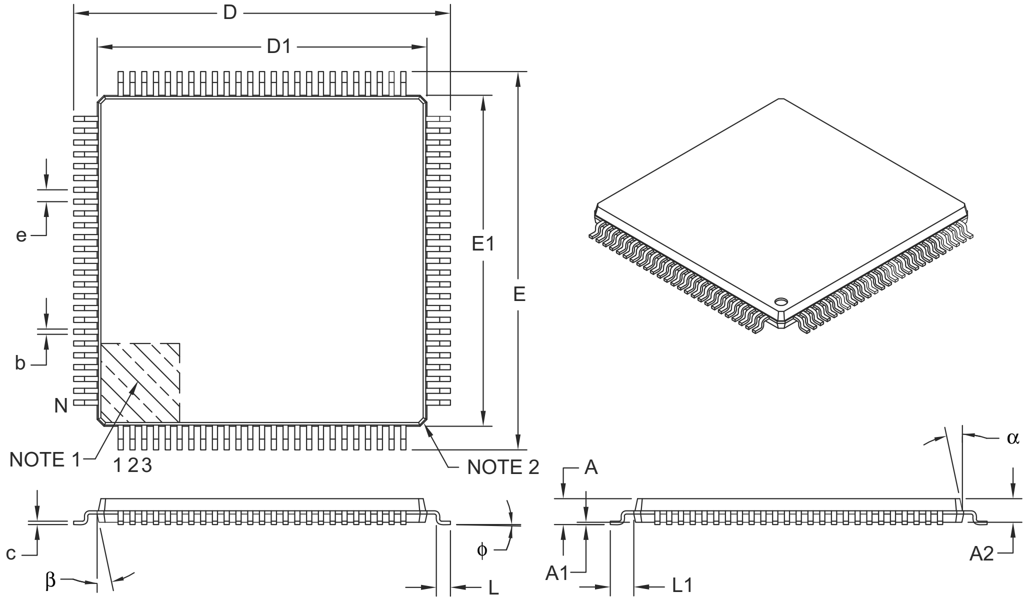
TABLE 26-8: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	D_{CLK}	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	MILLIMETERS	
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

    BSC: Basic Dimension. Theoretically exact value shown without tolerances.
    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B